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on one side thereof, the substrate having protrusions formed in the internal wall surfaces of the penetrating holes by the material constituting the substrate.--

--56. The substrate as defined in claim 53, wherein the adhesive material is an adhesive tape.--

--57. The substrate as defined in claim 55, wherein the adhesive material is an adhesive tape.--

Sub 47
--58. The substrate as defined in claim 53, wherein the conductive member includes first and second portions, a part of the first portion positioned over each of the penetrating holes, the first portion having a greater width than the second portion.--

--59. The substrate as defined in claim 55, wherein the conductive member includes first and second portions, a part of the first portion positioned over each of the penetrating holes, the first portion having a greater width than the second portion.--

--60. The substrate as defined in claim 53, wherein the substrate is an insulating substrate.--

--61. The substrate as defined in claim 55, wherein the substrate is an insulating substrate.--

--62. The substrate as defined in claim 53, wherein the substrate is a printed substrate.--

--63. The substrate as defined in claim 55, wherein the substrate is a printed substrate.--

--64. The substrate as defined in claim 53, further comprising an anisotropic conductive material having conductive particles dispersed in an adhesive.--

--65. The substrate as defined in claim 55, further comprising an anisotropic conductive material having conductive particles dispersed in an adhesive.--

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Sub 57
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--66. A method of manufacturing a substrate comprising:

providing a substrate with an adhesive material provided on one surface thereof;
carrying out punching from the side of the substrate on which the adhesive material is provided and in the direction of the opposite side thereof to form penetrating holes and to draw a part of the adhesive material into the penetrating holes; and
adhering a conductive member over a particular region on the one surface including the penetrating holes on the substrate through the adhesive material.--

--67. A method of manufacturing a substrate comprising providing a substrate of a material of a higher elasticity than external electrodes, having penetrating holes in which the internal wall surfaces have protrusions, and having a conductive member directly formed over a region including the penetrating holes.--

--68. The method of manufacturing a substrate as defined in claim 67, wherein the penetrating holes are formed by a laser.--

--69. The method of manufacturing a substrate as defined in claim 67, wherein the penetrating holes are formed by wet etching.--

Sub 67
--70. The method of manufacturing a substrate as defined in claim 66, wherein the substrate is either of an insulating film and a printed substrate.--

--71. The method of manufacturing a substrate as defined in claim 67, wherein the substrate is either of an insulating film and a printed substrate.--

--72. The method of manufacturing a substrate as defined in claim 66, after adhering the conductive member, further comprising providing an adhesive in which an anisotropic conductive material having conductive particles dispersed.--